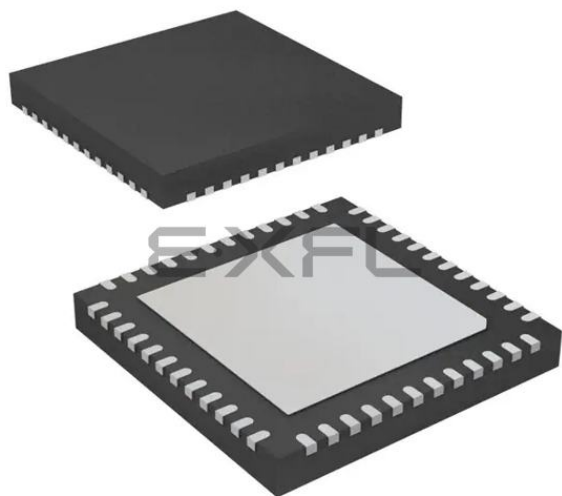




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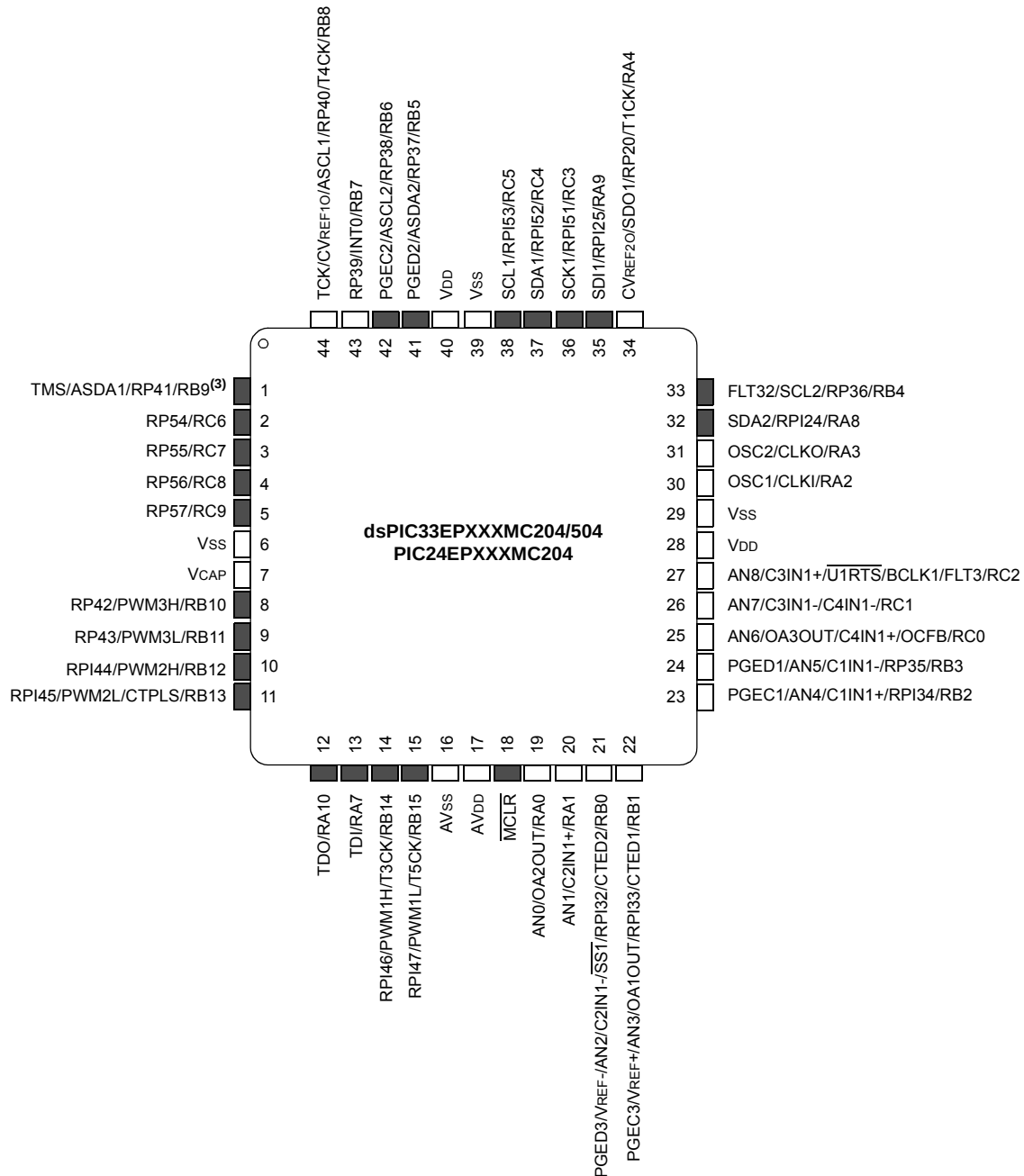
Details

Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	70 MIPS
Connectivity	CANbus, I ² C, IrDA, LINbus, QEI, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, Motor Control PWM, POR, PWM, WDT
Number of I/O	35
Program Memory Size	32KB (10.7K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	2K x 16
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 9x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	48-UQFN Exposed Pad
Supplier Device Package	48-UQFN (6x6)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33ep32mc504-i-mv

Pin Diagrams (Continued)

44-Pin TQFP^(1,2)

■ = Pins are up to 5V tolerant



- Note 1:** The RPN/RPIN pins can be used by any remappable peripheral with some limitation. See **Section 11.4 "Peripheral Pin Select (PPS)"** for available peripherals and for information on limitations.
- Note 2:** Every I/O port pin (RAX-RGX) can be used as a Change Notification pin (CNAX-CNGX). See **Section 11.0 "I/O Ports"** for more information.
- Note 3:** There is an internal pull-up resistor connected to the TMS pin when the JTAG interface is active. See the JTAGEN bit field in Table 27-2.

FIGURE 4-8: DATA MEMORY MAP FOR dsPIC33EP64MC20X/50X AND dsPIC33EP64GP50X DEVICES

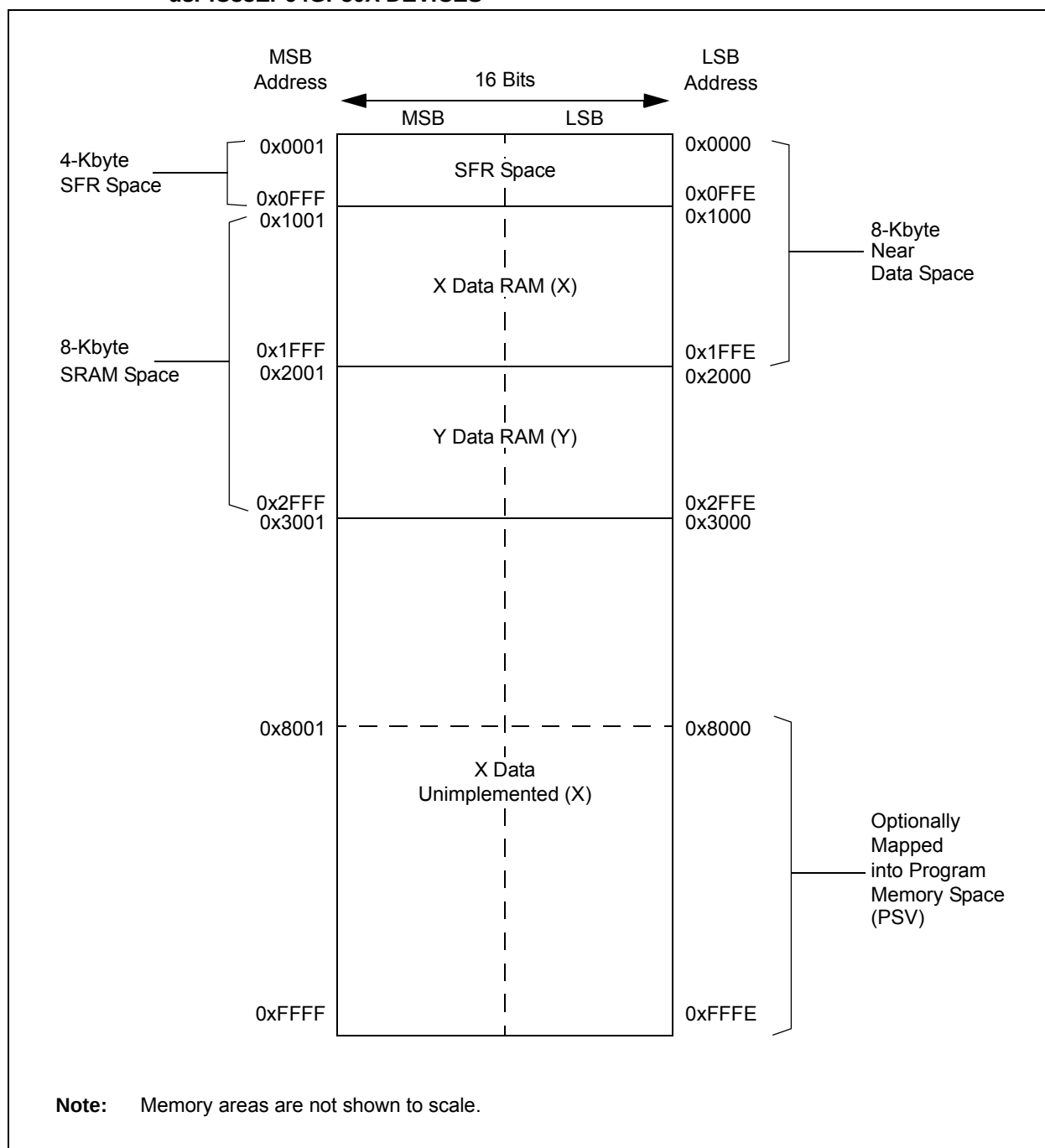


TABLE 4-6: INTERRUPT CONTROLLER REGISTER MAP FOR dsPIC33EPXXXMC20X DEVICES ONLY (CONTINUED)

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
IPC35	0886	—	JTAGIP<2:0>			—	ICDIP<2:0>			—	—	—	—	—	—	—	—	4400
IPC36	0888	—	PTG0IP<2:0>			—	PTGWDTIP<2:0>			—	PTGSTEIP<2:0>			—	—	—	—	4440
IPC37	088A	—	—	—	—	—	PTG3IP<2:0>			—	PTG2IP<2:0>			—	PTG1IP<2:0>			0444
INTCON1	08C0	NSTDIS	OVAERR	OVBERR	COVAERR	COVBERR	OVATE	OVATE	COVTE	SFTACERR	DIV0ERR	DMACERR	MATHERR	ADDRERR	STKERR	OSCFAIL	—	0000
INTCON2	08C2	GIE	DISI	SWTRAP	—	—	—	—	—	—	—	—	—	—	INT2EP	INT1EP	INT0EP	8000
INTCON3	08C4	—	—	—	—	—	—	—	—	—	—	DAE	DOOVR	—	—	—	—	0000
INTCON4	08C6	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	SGHT	0000
INTTREG	08C8	—	—	—	—	ILR<3:0>				VECNUM<7:0>								0000

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-41: PMD REGISTER MAP FOR dsPIC33EPXXXMC20X DEVICES ONLY

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
PMD1	0760	T5MD	T4MD	T3MD	T2MD	T1MD	QE1MD	PWMMD	—	I2C1MD	U2MD	U1MD	SPI2MD	SPI1MD	—	—	AD1MD	0000
PMD2	0762	—	—	—	—	IC4MD	IC3MD	IC2MD	IC1MD	—	—	—	—	OC4MD	OC3MD	OC2MD	OC1MD	0000
PMD3	0764	—	—	—	—	—	CMPMD	—	—	CRCMD	—	—	—	—	—	I2C2MD	—	0000
PMD4	0766	—	—	—	—	—	—	—	—	—	—	—	—	REFOMD	CTMUMD	—	—	0000
PMD6	076A	—	—	—	—	—	PWM3MD	PWM2MD	PWM1MD	—	—	—	—	—	—	—	—	0000
PMD7	076C	—	—	—	—	—	—	—	—	—	—	—	DMA0MD	PTGMD	—	—	—	0000
													DMA1MD					
													DMA2MD					
													DMA3MD					

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

4.8.1 DATA ACCESS FROM PROGRAM MEMORY USING TABLE INSTRUCTIONS

The TBLRDH and TBLWTH instructions offer a direct method of reading or writing the lower word of any address within the Program Space without going through Data Space. The TBLRDH and TBLWTH instructions are the only method to read or write the upper 8 bits of a Program Space word as data.

The PC is incremented by two for each successive 24-bit program word. This allows program memory addresses to directly map to Data Space addresses. Program memory can thus be regarded as two 16-bit-wide word address spaces, residing side by side, each with the same address range. TBLRDH and TBLWTH access the space that contains the least significant data word. TBLRDH and TBLWTH access the space that contains the upper data byte.

Two table instructions are provided to move byte or word-sized (16-bit) data to and from Program Space. Both function as either byte or word operations.

- TBLRDH (Table Read High):
 - In Word mode, this instruction maps the lower word of the Program Space location ($P<15:0>$) to a data address ($D<15:0>$)

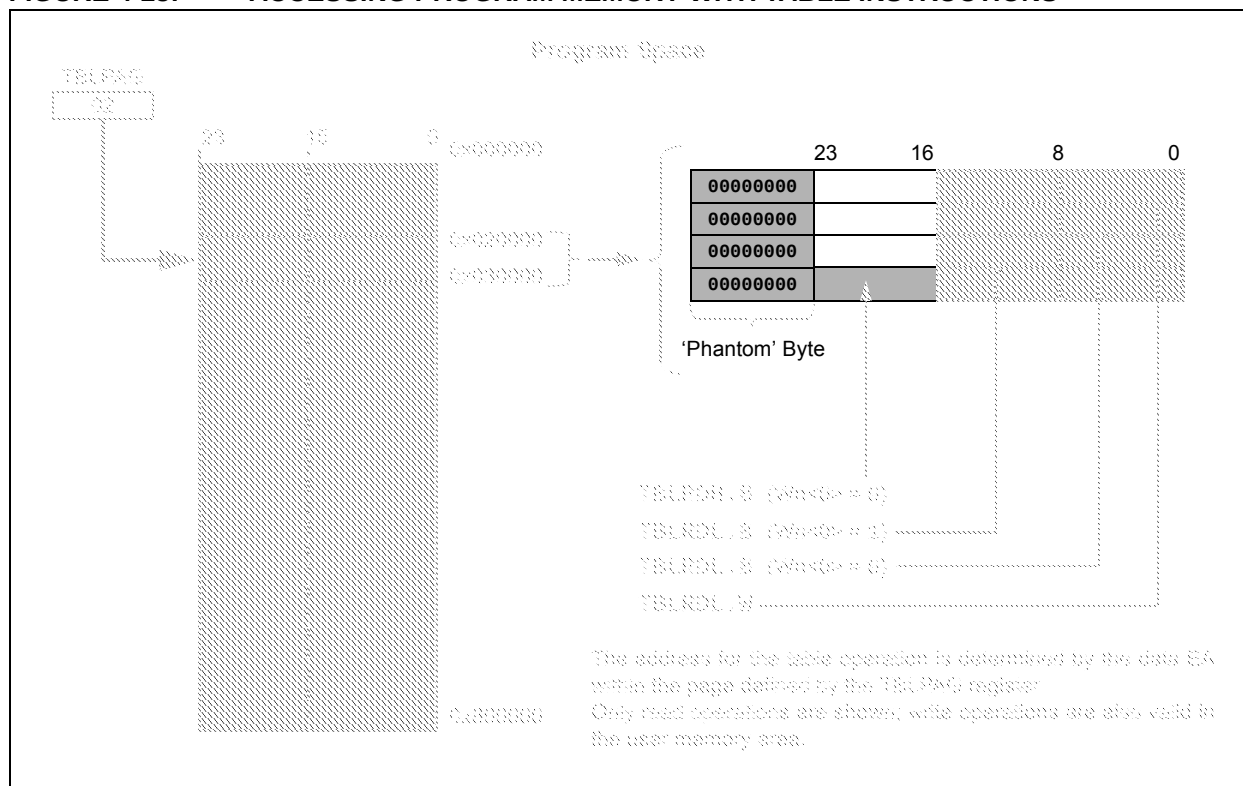
- In Byte mode, either the upper or lower byte of the lower program word is mapped to the lower byte of a data address. The upper byte is selected when Byte Select is '1'; the lower byte is selected when it is '0'.

- TBLRDH (Table Read High):
 - In Word mode, this instruction maps the entire upper word of a program address ($P<23:16>$) to a data address. The 'phantom' byte ($D<15:8>$) is always '0'.
 - In Byte mode, this instruction maps the upper or lower byte of the program word to $D<7:0>$ of the data address in the TBLRDH instruction. The data is always '0' when the upper 'phantom' byte is selected (Byte Select = 1).

In a similar fashion, two table instructions, TBLWTH and TBLWTL, are used to write individual bytes or words to a Program Space address. The details of their operation are explained in **Section 5.0 "Flash Program Memory"**.

For all table operations, the area of program memory space to be accessed is determined by the Table Page register (TBLPAG). TBLPAG covers the entire program memory space of the device, including user application and configuration spaces. When $TBLPAG<7> = 0$, the table page is located in the user memory space. When $TBLPAG<7> = 1$, the page is located in configuration space.

FIGURE 4-23: ACCESSING PROGRAM MEMORY WITH TABLE INSTRUCTIONS



REGISTER 8-3: DMAxSTAH: DMA CHANNEL x START ADDRESS REGISTER A (HIGH)

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15				bit 8			

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
STA<23:16>							
bit 7				bit 0			

Legend:

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

-n = Value at POR

'1' = Bit is set

'0' = Bit is cleared

x = Bit is unknown

bit 15-8 **Unimplemented:** Read as '0'

bit 7-0 **STA<23:16>:** Primary Start Address bits (source or destination)

REGISTER 8-4: DMAxSTAL: DMA CHANNEL x START ADDRESS REGISTER A (LOW)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
STA<15:8>							
bit 15				bit 8			

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
STA<7:0>							
bit 7				bit 0			

Legend:

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

-n = Value at POR

'1' = Bit is set

'0' = Bit is cleared

x = Bit is unknown

bit 15-0 **STA<15:0>:** Primary Start Address bits (source or destination)

9.1 CPU Clocking System

The dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X family of devices provides six system clock options:

- Fast RC (FRC) Oscillator
- FRC Oscillator with Phase Locked Loop (PLL)
- FRC Oscillator with Postscaler
- Primary (XT, HS or EC) Oscillator
- Primary Oscillator with PLL
- Low-Power RC (LPRC) Oscillator

Instruction execution speed or device operating frequency, F_{CY} , is given by Equation 9-1.

EQUATION 9-1: DEVICE OPERATING FREQUENCY

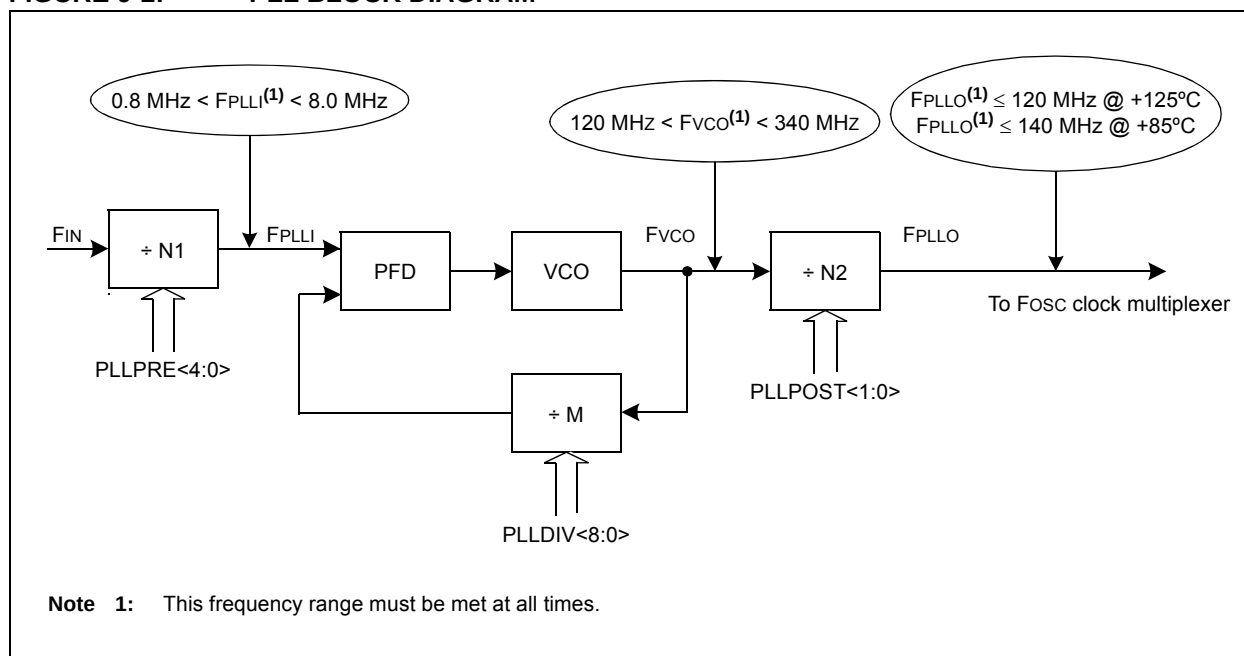
$$F_{CY} = F_{osc}/2$$

Figure 9-2 is a block diagram of the PLL module.

Equation 9-2 provides the relationship between input frequency (F_{IN}) and output frequency (F_{PLLO}). In clock modes S1 and S3, when the PLL output is selected, $F_{OSC} = F_{PLLO}$.

Equation 9-3 provides the relationship between input frequency (F_{IN}) and VCO frequency (F_{VCO}).

FIGURE 9-2: PLL BLOCK DIAGRAM



EQUATION 9-2: F_{PLLO} CALCULATION

$$F_{PLLO} = F_{IN} \times \left(\frac{M}{N1 \times N2} \right) = F_{IN} \times \left(\frac{(PLLDIV + 2)}{(PLLPRE + 2) \times 2(PLLPOST + 1)} \right)$$

Where:

$$N1 = PLLPRE + 2$$

$$N2 = 2 \times (PLLPOST + 1)$$

$$M = PLLDIV + 2$$

EQUATION 9-3: F_{VCO} CALCULATION

$$F_{VCO} = F_{IN} \times \left(\frac{M}{N1} \right) = F_{IN} \times \left(\frac{(PLLDIV + 2)}{(PLLPRE + 2)} \right)$$

REGISTER 11-6: RPINR11: PERIPHERAL PIN SELECT INPUT REGISTER 11

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	OCFAR<6:0>						
bit 7							bit 0

Legend:

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

-n = Value at POR

'1' = Bit is set

'0' = Bit is cleared

x = Bit is unknown

bit 15-7

Unimplemented: Read as '0'

bit 6-0

OCFAR<6:0>: Assign Output Compare Fault A (OCFA) to the Corresponding RPn Pin bits (see Table 11-2 for input pin selection numbers)

1111001 = Input tied to RPI121

.

.

.

0000001 = Input tied to CMP1

0000000 = Input tied to Vss

REGISTER 16-16: LEBCONx: PWMx LEADING-EDGE BLANKING CONTROL REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0	U-0
PHR	PHF	PLR	PLF	FLTLEBEN	CLLEBEN	—	—
bit 15						bit 8	
U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	BCH ⁽¹⁾	BCL ⁽¹⁾	BPHH	BPHL	BPLH	BPLL
bit 7						bit 0	

Legend:

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

-n = Value at POR

'1' = Bit is set

'0' = Bit is cleared

x = Bit is unknown

- bit 15 **PHR:** PWMxH Rising Edge Trigger Enable bit
1 = Rising edge of PWMxH will trigger Leading-Edge Blanking counter
0 = Leading-Edge Blanking ignores rising edge of PWMxH
- bit 14 **PHF:** PWMxH Falling Edge Trigger Enable bit
1 = Falling edge of PWMxH will trigger Leading-Edge Blanking counter
0 = Leading-Edge Blanking ignores falling edge of PWMxH
- bit 13 **PLR:** PWMxL Rising Edge Trigger Enable bit
1 = Rising edge of PWMxL will trigger Leading-Edge Blanking counter
0 = Leading-Edge Blanking ignores rising edge of PWMxL
- bit 12 **PLF:** PWMxL Falling Edge Trigger Enable bit
1 = Falling edge of PWMxL will trigger Leading-Edge Blanking counter
0 = Leading-Edge Blanking ignores falling edge of PWMxL
- bit 11 **FLTLEBEN:** Fault Input Leading-Edge Blanking Enable bit
1 = Leading-Edge Blanking is applied to selected Fault input
0 = Leading-Edge Blanking is not applied to selected Fault input
- bit 10 **CLLEBEN:** Current-Limit Leading-Edge Blanking Enable bit
1 = Leading-Edge Blanking is applied to selected current-limit input
0 = Leading-Edge Blanking is not applied to selected current-limit input
- bit 9-6 **Unimplemented:** Read as '0'
- bit 5 **BCH:** Blanking in Selected Blanking Signal High Enable bit⁽¹⁾
1 = State blanking (of current-limit and/or Fault input signals) when selected blanking signal is high
0 = No blanking when selected blanking signal is high
- bit 4 **BCL:** Blanking in Selected Blanking Signal Low Enable bit⁽¹⁾
1 = State blanking (of current-limit and/or Fault input signals) when selected blanking signal is low
0 = No blanking when selected blanking signal is low
- bit 3 **BPHH:** Blanking in PWMxH High Enable bit
1 = State blanking (of current-limit and/or Fault input signals) when PWMxH output is high
0 = No blanking when PWMxH output is high
- bit 2 **BPHL:** Blanking in PWMxH Low Enable bit
1 = State blanking (of current-limit and/or Fault input signals) when PWMxH output is low
0 = No blanking when PWMxH output is low
- bit 1 **BPLH:** Blanking in PWMxL High Enable bit
1 = State blanking (of current-limit and/or Fault input signals) when PWMxL output is high
0 = No blanking when PWMxL output is high
- bit 0 **BPLL:** Blanking in PWMxL Low Enable bit
1 = State blanking (of current-limit and/or Fault input signals) when PWMxL output is low
0 = No blanking when PWMxL output is low

Note 1: The blanking signal is selected via the BLANKSELx bits in the AUXCONx register.

REGISTER 16-17: LEBDLYx: PWMx LEADING-EDGE BLANKING DELAY REGISTER

U-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	—	—	LEB<11:8>			
bit 15				bit 8			

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
LEB<7:0>							
bit 7				bit 0			

Legend:

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

-n = Value at POR

'1' = Bit is set

'0' = Bit is cleared

x = Bit is unknown

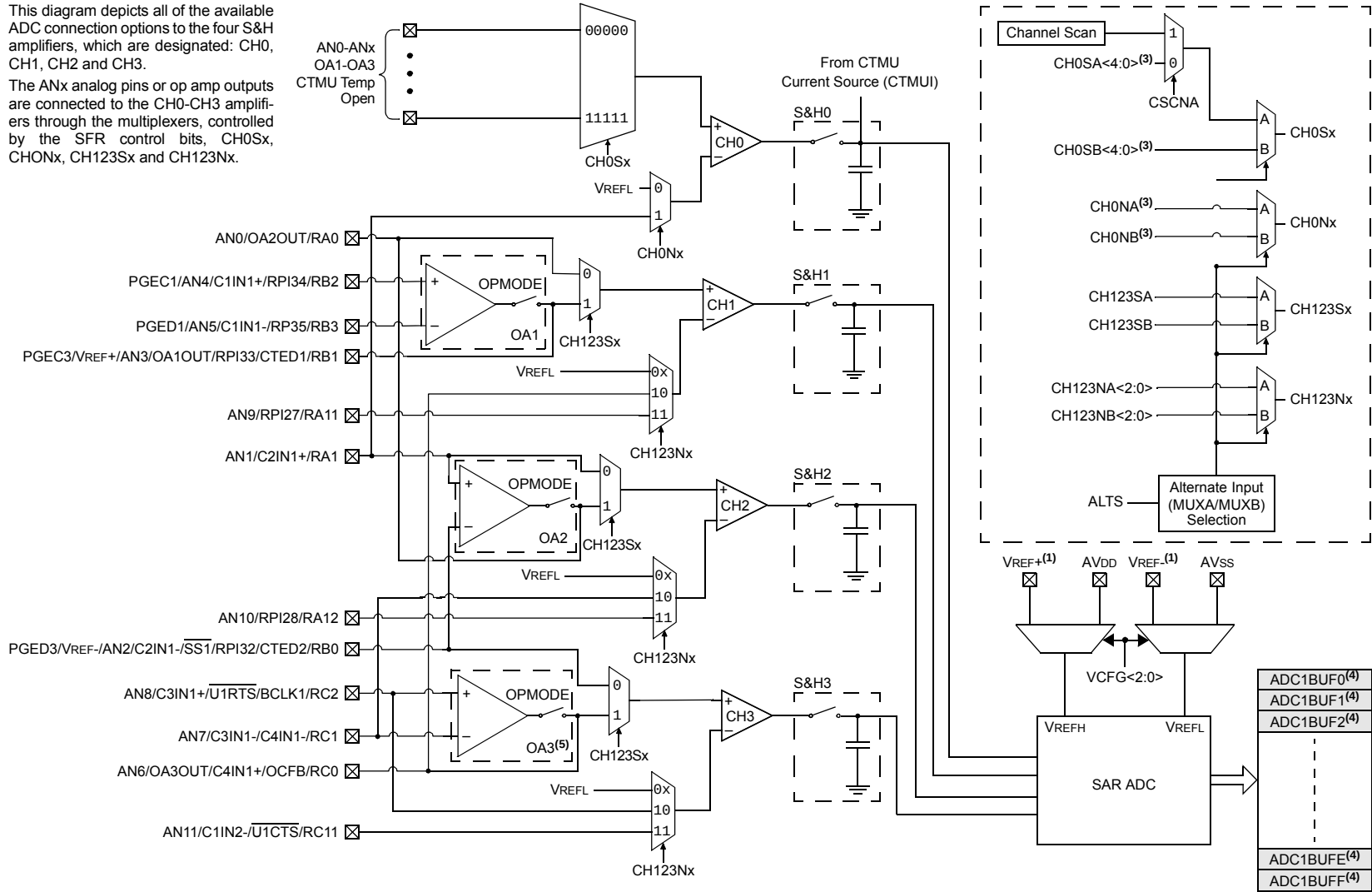
bit 15-12 **Unimplemented:** Read as '0'

bit 11-0 **LEB<11:0>:** Leading-Edge Blanking Delay for Current-Limit and Fault Inputs bits

FIGURE 23-1: ADC MODULE BLOCK DIAGRAM WITH CONNECTION OPTIONS FOR ANx PINS AND OP AMPS

This diagram depicts all of the available ADC connection options to the four S&H amplifiers, which are designated: CH0, CH1, CH2 and CH3.

The ANx analog pins or op amp outputs are connected to the CH0-CH3 amplifiers through the multiplexers, controlled by the SFR control bits, CH0Sx, CHONx, CH123Sx and CH123Nx.



- Note**
- 1: VREF+, VREF- inputs can be multiplexed with other analog inputs.
 - 2: Channels 1, 2 and 3 are not applicable for the 12-bit mode of operation.
 - 3: These bits can be updated with Step commands from the PTG module. See Section 24.0 "Peripheral Trigger Generator (PTG) Module" for more information.
 - 4: When ADDMAEN (AD1CON4<8>) = 1, enabling DMA, only ADC1BUF0 is used.
 - 5: OA3 is not available for 28-pin devices.

NOTES:

27.2 User ID Words

dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X devices contain four User ID Words, located at addresses, 0x800FF8 through 0x800FFE. The User ID Words can be used for storing product information such as serial numbers, system manufacturing dates, manufacturing lot numbers and other application-specific information.

The User ID Words register map is shown in Table 27-3.

TABLE 27-3: USER ID WORDS REGISTER MAP

File Name	Address	Bits 23-16	Bits 15-0
FUID0	0x800FF8	—	UID0
FUID1	0x800FFA	—	UID1
FUID2	0x800FFC	—	UID2
FUID3	0x800FFE	—	UID3

Legend: — = unimplemented, read as '1'.

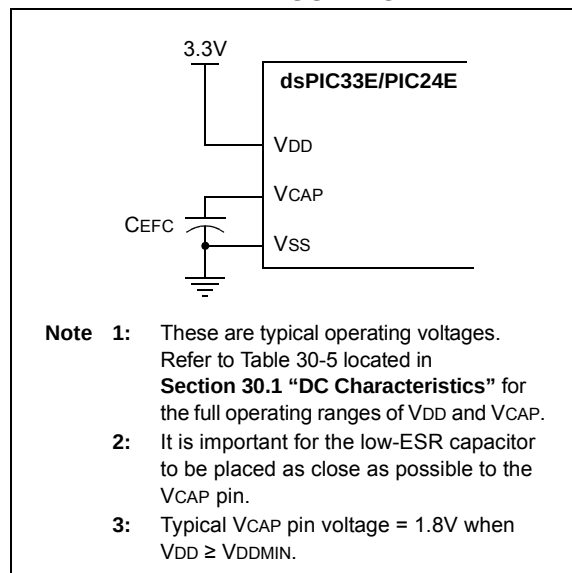
27.3 On-Chip Voltage Regulator

All of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X devices power their core digital logic at a nominal 1.8V. This can create a conflict for designs that are required to operate at a higher typical voltage, such as 3.3V. To simplify system design, all devices in the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X family incorporate an on-chip regulator that allows the device to run its core logic from VDD.

The regulator provides power to the core from the other VDD pins. A low-ESR (less than 1 Ohm) capacitor (such as tantalum or ceramic) must be connected to the VCAP pin (Figure 27-1). This helps to maintain the stability of the regulator. The recommended value for the filter capacitor is provided in Table 30-5 located in Section 30.0 "Electrical Characteristics".

Note: It is important for the low-ESR capacitor to be placed as close as possible to the VCAP pin.

FIGURE 27-1: CONNECTIONS FOR THE ON-CHIP VOLTAGE REGULATOR^(1,2,3)



27.4 Brown-out Reset (BOR)

The Brown-out Reset (BOR) module is based on an internal voltage reference circuit that monitors the regulated supply voltage, VCAP. The main purpose of the BOR module is to generate a device Reset when a brown-out condition occurs. Brown-out conditions are generally caused by glitches on the AC mains (for example, missing portions of the AC cycle waveform due to bad power transmission lines or voltage sags due to excessive current draw when a large inductive load is turned on).

A BOR generates a Reset pulse, which resets the device. The BOR selects the clock source, based on the device Configuration bit values (FNOSC<2:0> and POSCMD<1:0>).

If an oscillator mode is selected, the BOR activates the Oscillator Start-up Timer (OST). The system clock is held until OST expires. If the PLL is used, the clock is held until the LOCK bit (OSCCON<5>) is '1'.

Concurrently, the PWRT Time-out (TPWRT) is applied before the internal Reset is released. If TPWRT = 0 and a crystal oscillator is being used, then a nominal delay of TFSCM is applied. The total delay in this case is TFSCM. Refer to Parameter SY35 in Table 30-22 of Section 30.0 "Electrical Characteristics" for specific TFSCM values.

The BOR status bit (RCON<1>) is set to indicate that a BOR has occurred. The BOR circuit continues to operate while in Sleep or Idle modes and resets the device should VDD fall below the BOR threshold voltage.

TABLE 30-12: DC CHARACTERISTICS: I/O PIN OUTPUT SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	Symbol	Characteristic	Min.	Typ.	Max.	Units	Conditions
DO10	VOL	Output Low Voltage 4x Sink Driver Pins ⁽²⁾	—	—	0.4	V	VDD = 3.3V, IOL ≤ 6 mA, -40°C ≤ TA ≤ +85°C IOL ≤ 5 mA, +85°C < TA ≤ +125°C
		Output Low Voltage 8x Sink Driver Pins ⁽³⁾	—	—	0.4	V	VDD = 3.3V, IOL ≤ 12 mA, -40°C ≤ TA ≤ +85°C IOL ≤ 8 mA, +85°C < TA ≤ +125°C
DO20	VOH	Output High Voltage 4x Source Driver Pins ⁽²⁾	2.4	—	—	V	IOH ≥ -10 mA, VDD = 3.3V
		Output High Voltage 8x Source Driver Pins ⁽³⁾	2.4	—	—	V	IOH ≥ -15 mA, VDD = 3.3V
DO20A	VOH1	Output High Voltage 4x Source Driver Pins ⁽²⁾	1.5 ⁽¹⁾	—	—	V	IOH ≥ -14 mA, VDD = 3.3V
			2.0 ⁽¹⁾	—	—		IOH ≥ -12 mA, VDD = 3.3V
			3.0 ⁽¹⁾	—	—		IOH ≥ -7 mA, VDD = 3.3V
		Output High Voltage 8x Source Driver Pins ⁽³⁾	1.5 ⁽¹⁾	—	—	V	IOH ≥ -22 mA, VDD = 3.3V
			2.0 ⁽¹⁾	—	—		IOH ≥ -18 mA, VDD = 3.3V
			3.0 ⁽¹⁾	—	—		IOH ≥ -10 mA, VDD = 3.3V

Note 1: Parameters are characterized but not tested.

2: Includes all I/O pins that are not 8x Sink Driver pins (see below).

3: Includes the following pins:

For devices with less than 64 pins: RA3, RA4, RA9, RB<7:15> and RC3

For 64-pin devices: RA4, RA9, RB<7:15>, RC3 and RC15

TABLE 30-13: ELECTRICAL CHARACTERISTICS: BOR

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) ⁽¹⁾ Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	Symbol	Characteristic	Min. ⁽²⁾	Typ.	Max.	Units	Conditions
BO10	VBOR	BOR Event on VDD Transition High-to-Low	2.65	—	2.95	V	VDD (Notes 2 and 3)

Note 1: Device is functional at VBORMIN < VDD < VDDMIN, but will have degraded performance. Device functionality is tested, but not characterized. Analog modules (ADC, op amp/comparator and comparator voltage reference) may have degraded performance.

2: Parameters are for design guidance only and are not tested in manufacturing.

3: The VBOR specification is relative to VDD.

TABLE 30-18: PLL CLOCK TIMING SPECIFICATIONS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	Symbol	Characteristic	Min.	Typ. ⁽¹⁾	Max.	Units	Conditions
OS50	FPLLI	PLL Voltage Controlled Oscillator (VCO) Input Frequency Range	0.8	—	8.0	MHz	ECPLL, XTPLL modes
OS51	FVCO	On-Chip VCO System Frequency	120	—	340	MHz	
OS52	TLOCK	PLL Start-up Time (Lock Time)	0.9	1.5	3.1	ms	
OS53	DCLK	CLKO Stability (Jitter) ⁽²⁾	-3	0.5	3	%	

Note 1: Data in "Typical" column is at 3.3V, +25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

2: This jitter specification is based on clock cycle-by-clock cycle measurements. To get the effective jitter for individual time bases, or communication clocks used by the application, use the following formula:

$$\text{Effective Jitter} = \frac{DCLK}{\sqrt{\frac{FOSC}{\text{Time Base or Communication Clock}}}}$$

For example, if Fosc = 120 MHz and the SPIx bit rate = 10 MHz, the effective jitter is as follows:

$$\text{Effective Jitter} = \frac{DCLK}{\sqrt{\frac{120}{10}}} = \frac{DCLK}{\sqrt{12}} = \frac{DCLK}{3.464}$$

TABLE 30-19: INTERNAL FRC ACCURACY

AC CHARACTERISTICS		Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended					
Param No.	Characteristic	Min.	Typ.	Max.	Units	Conditions	
Internal FRC Accuracy @ FRC Frequency = 7.37 MHz ⁽¹⁾							
F20a	FRC	-1.5	0.5	+1.5	%	-40°C ≤ TA ≤ -10°C	VDD = 3.0-3.6V
		-1	0.5	+1	%	-10°C ≤ TA ≤ +85°C	VDD = 3.0-3.6V
F20b	FRC	-2	1	+2	%	+85°C ≤ TA ≤ +125°C	VDD = 3.0-3.6V

Note 1: Frequency is calibrated at +25°C and 3.3V. TUNx bits can be used to compensate for temperature drift.

TABLE 30-20: INTERNAL LPRC ACCURACY

AC CHARACTERISTICS		Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for Industrial $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ for Extended					
Param No.	Characteristic	Min.	Typ.	Max.	Units	Conditions	
LPRC @ 32.768 kHz ⁽¹⁾							
F21a	LPRC	-30	—	+30	%	$-40^{\circ}\text{C} \leq T_A \leq -10^{\circ}\text{C}$	VDD = 3.0-3.6V
		-20	—	+20	%	$-10^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$	VDD = 3.0-3.6V
F21b	LPRC	-30	—	+30	%	$+85^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$	VDD = 3.0-3.6V

Note 1: The change of LPRC frequency as VDD changes.

**TABLE 30-37: SPI2 SLAVE MODE (FULL-DUPLEX, CKE = 1, CKP = 0, SMP = 0)
TIMING REQUIREMENTS**

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for Industrial $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ for Extended				
Param.	Symbol	Characteristic ⁽¹⁾	Min.	Typ. ⁽²⁾	Max.	Units	Conditions
SP70	FscP	Maximum SCK2 Input Frequency	—	—	Lesser of Fp or 15	MHz	(Note 3)
SP72	TscF	SCK2 Input Fall Time	—	—	—	ns	See Parameter DO32 (Note 4)
SP73	TscR	SCK2 Input Rise Time	—	—	—	ns	See Parameter DO31 (Note 4)
SP30	TdoF	SDO2 Data Output Fall Time	—	—	—	ns	See Parameter DO32 (Note 4)
SP31	TdoR	SDO2 Data Output Rise Time	—	—	—	ns	See Parameter DO31 (Note 4)
SP35	Tsch2doV, TscL2doV	SDO2 Data Output Valid after SCK2 Edge	—	6	20	ns	
SP36	TdoV2scH, TdoV2scL	SDO2 Data Output Setup to First SCK2 Edge	30	—	—	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDI2 Data Input to SCK2 Edge	30	—	—	ns	
SP41	Tsch2diL, TscL2diL	Hold Time of SDI2 Data Input to SCK2 Edge	30	—	—	ns	
SP50	TssL2scH, TssL2scL	$\overline{\text{SS}}2 \downarrow$ to SCK2 $\uparrow$ or SCK2 $\downarrow$ Input	120	—	—	ns	
SP51	TssH2doZ	$\overline{\text{SS}}2 \uparrow$ to SDO2 Output High-Impedance	10	—	50	ns	(Note 4)
SP52	Tsch2ssH, TscL2ssH	$\overline{\text{SS}}2 \uparrow$ after SCK2 Edge	$1.5 T_{CY} + 40$	—	—	ns	(Note 4)
SP60	TssL2doV	SDO2 Data Output Valid after $\overline{\text{SS}}2$ Edge	—	—	50	ns	

Note 1: These parameters are characterized, but are not tested in manufacturing.

2: Data in “Typical” column is at 3.3V, +25°C unless otherwise stated.

3: The minimum clock period for SCK2 is 66.7 ns. Therefore, the SCK2 clock generated by the master must not violate this specification.

4: Assumes 50 pF load on all SPI2 pins.

FIGURE 30-19: SPI2 SLAVE MODE (FULL-DUPLEX, CKE = 1, CKP = 1, SMP = 0)
TIMING CHARACTERISTICS

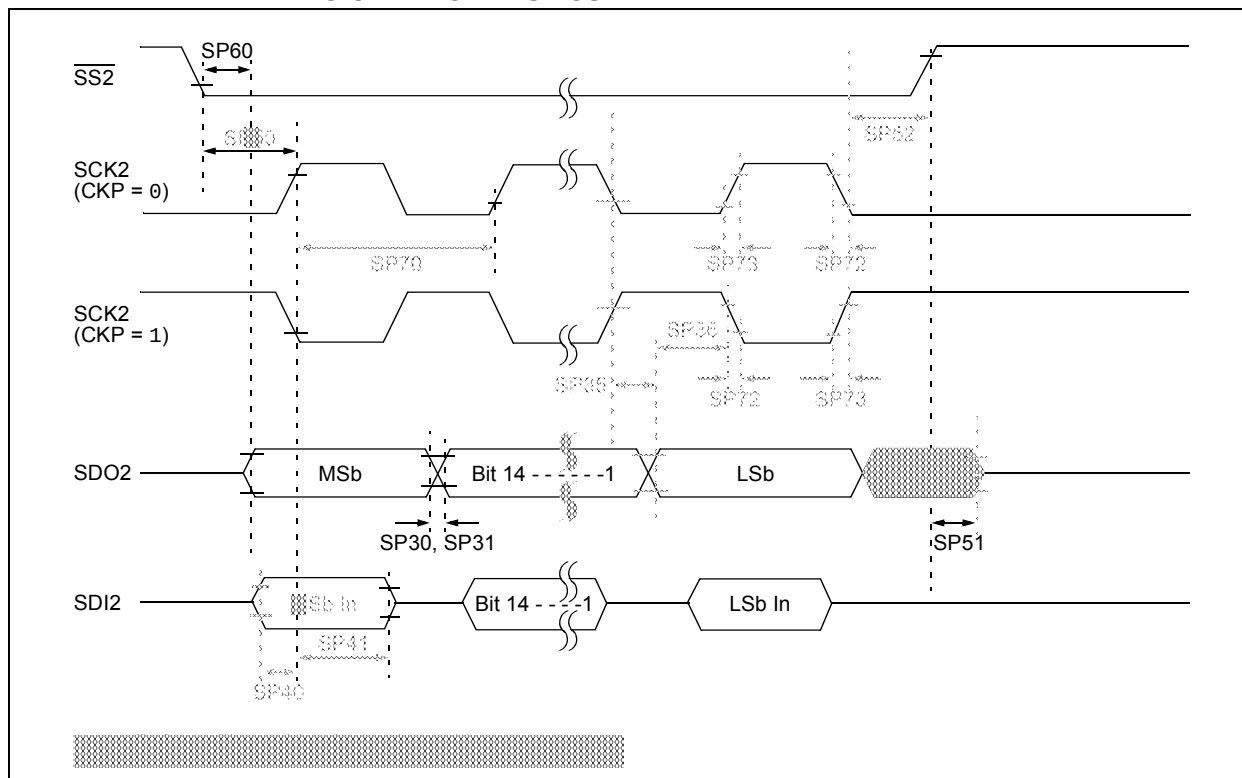


FIGURE 30-30: I2Cx BUS START/STOP BITS TIMING CHARACTERISTICS (MASTER MODE)

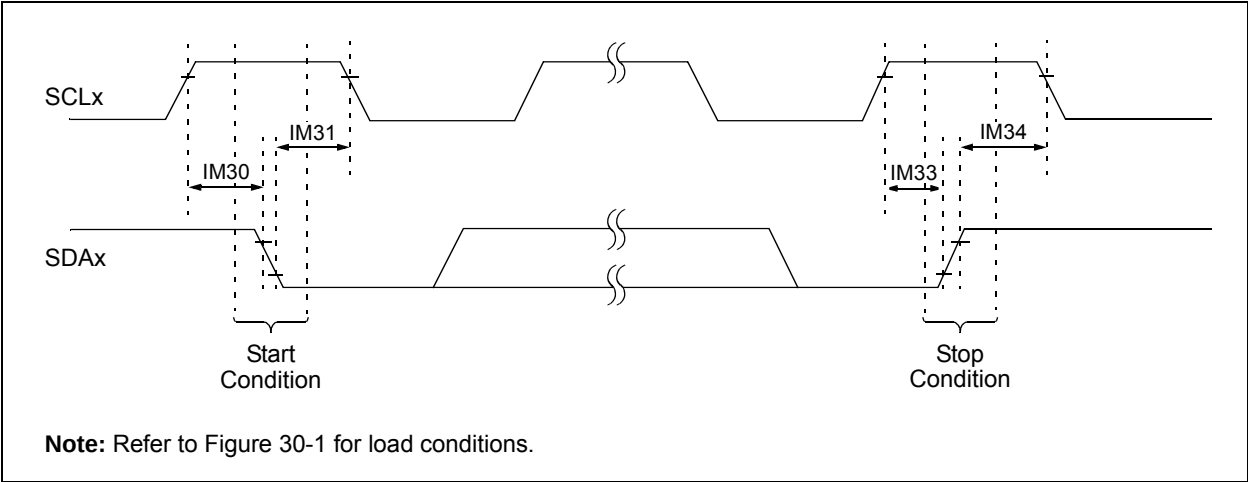
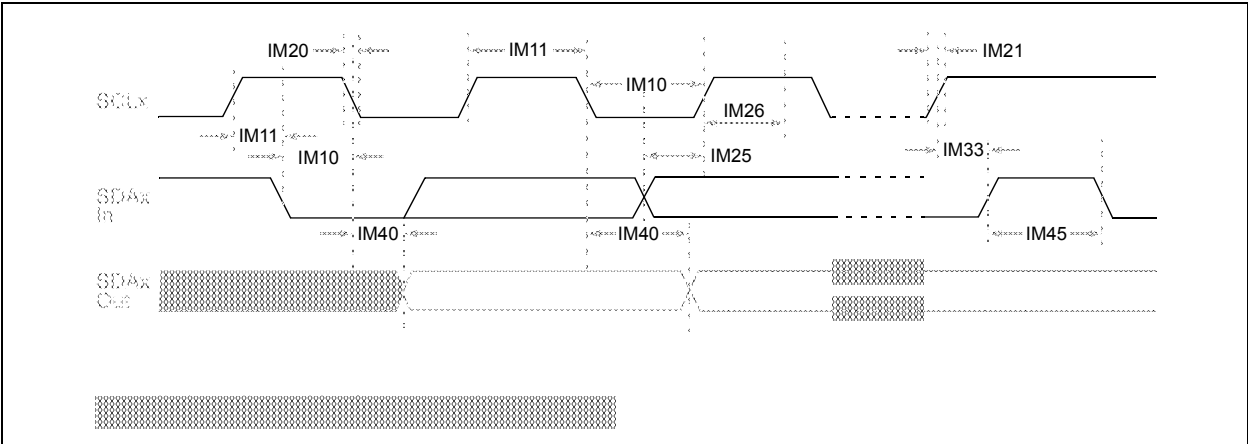


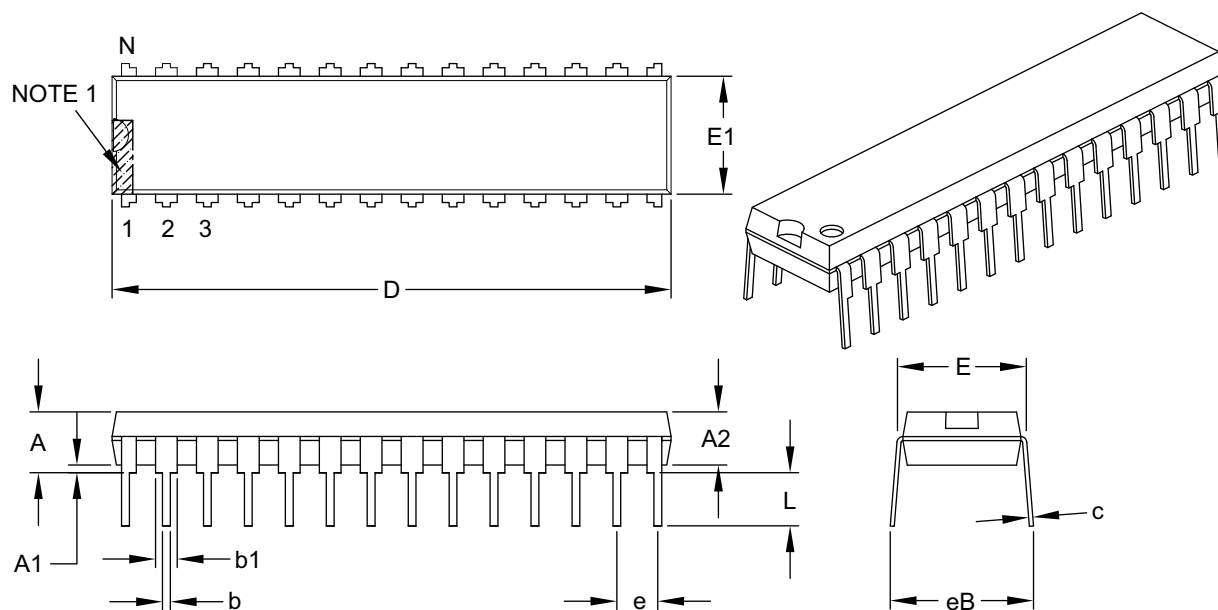
FIGURE 30-31: I2Cx BUS DATA TIMING CHARACTERISTICS (MASTER MODE)



33.2 Package Details

28-Lead Skinny Plastic Dual In-Line (SP) – 300 mil Body [SPDIP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Units		INCHES		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N	28		
Pitch	e	.100 BSC		
Top to Seating Plane	A	–	–	.200
Molded Package Thickness	A2	.120	.135	.150
Base to Seating Plane	A1	.015	–	–
Shoulder to Shoulder Width	E	.290	.310	.335
Molded Package Width	E1	.240	.285	.295
Overall Length	D	1.345	1.365	1.400
Tip to Seating Plane	L	.110	.130	.150
Lead Thickness	c	.008	.010	.015
Upper Lead Width	b1	.040	.050	.070
Lower Lead Width	b	.014	.018	.022
Overall Row Spacing §	eB	–	–	.430

Notes:

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- § Significant Characteristic.
- Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" per side.
- Dimensioning and tolerancing per ASME Y14.5M.
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-070B

P

Packaging	479
Details	505
Marking	479, 481
Peripheral Module Disable (PMD).....	165
Peripheral Pin Select (PPS)	175
Available Peripherals	175
Available Pins	175
Control	175
Control Registers	183
Input Mapping	176
Output Selection for Remappable Pins	180
Pin Selection for Selectable Input Sources	178
Selectable Input Sources	177
Peripheral Trigger Generator (PTG) Module.....	337
PICkit 3 In-Circuit Debugger/Programmer	399
Pinout I/O Descriptions (table)	26
Power-Saving Features.....	163
Clock Frequency	163
Clock Switching	163
Instruction-Based Modes	163
Idle	164
Interrupts Coincident with Power	
Save Instructions	164
Sleep	164
Resources	165
Program Address Space	45
Construction	117
Data Access from Program Memory Using	
Table Instructions.....	118
Memory Map (dsPIC33EP128GP50X,	
dsPIC33EP128MC20X/50X,	
PIC24EP128GP/MC20X Devices)	47
Memory Map (dsPIC33EP256GP50X,	
dsPIC33EP256MC20X/50X,	
PIC24EP256GP/MC20X Devices)	48
Memory Map (dsPIC33EP32GP50X,	
dsPIC33EP32MC20X/50X,	
PIC24EP32GP/MC20X Devices)	45
Memory Map (dsPIC33EP512GP50X,	
dsPIC33EP512MC20X/50X,	
PIC24EP512GP/MC20X Devices)	49
Memory Map (dsPIC33EP64GP50X,	
dsPIC33EP64MC20X/50X,	
PIC24EP64GP/MC20X Devices)	46
Table Read High Instructions	
TBLRDH	118
Table Read Low Instructions (TBLRDL)	118
Program Memory	
Organization	50
Reset Vector	50
Programmable CRC Generator.....	373
Control Registers	375
Overview	374
Resources	374
Programmer's Model.....	37
Register Descriptions	37
PTG	
Control Registers	340
Introduction	337
Output Descriptions	353
Resources	339
Step Commands and Format.....	350

Q

QE1	
Control Registers	252
Resources	251
Quadrature Encoder Interface (QE1).....	249

R

Register Maps	
ADC1	84
CPU Core (dsPIC33EPXXXMC20X/50X,	
dsPIC33EPXXXGP50X Devices)	63
CPU Core (PIC24EPXXXGP/MC20X Devices)	65
CRC	88
CTMU	97
DMAC	98
ECAN1 (When WIN (C1CTRL1) = 0 or 1)	
for dsPIC33EPXXXMC/GP50X Devices.....	85
ECAN1 (When WIN (C1CTRL1) = 0) for	
dsPIC33EPXXXMC/GP50X Devices	85
ECAN1 (WIN (C1CTRL1) = 1) for	
dsPIC33EPXXXMC/GP50X Devices	86
I2C1 and I2C2	82
Input Capture 1 through Input Capture 4	76
Interrupt Controller	
(dsPIC33EPXXXGP50X Devices)	69
Interrupt Controller	
(dsPIC33EPXXXMC20X Devices).....	71
Interrupt Controller	
(dsPIC33EPXXXMC50X Devices).....	73
Interrupt Controller	
(PIC24EPXXXGP20X Devices)	66
Interrupt Controller	
(PIC24EPXXXMC20X Devices)	67
JTAG Interface	97
NVM.....	93
Op Amp/Comparator.....	97
Output Compare 1 through Output Compare 4	77
Peripheral Pin Select Input	
(dsPIC33EPXXXGP50X Devices)	91
Peripheral Pin Select Input	
(dsPIC33EPXXXMC20X Devices).....	92
Peripheral Pin Select Input	
(dsPIC33EPXXXMC50X Devices).....	91
Peripheral Pin Select Input	
(PIC24EPXXXGP20X Devices).....	90
Peripheral Pin Select Input	
(PIC24EPXXXMC20X Devices)	90
Peripheral Pin Select Output	
(dsPIC33EPXXXGP/MC202/502,	
PIC24EPXXXGP/MC202 Devices).....	88
Peripheral Pin Select Output	
(dsPIC33EPXXXGP/MC203/503,	
PIC24EPXXXGP/MC203 Devices).....	88
Peripheral Pin Select Output	
(dsPIC33EPXXXGP/MC204/504,	
PIC24EPXXXGP/MC204 Devices).....	89
Peripheral Pin Select Output	
(dsPIC33EPXXXGP/MC206/506,	
PIC24EPXXXGP/MC206 Devices)	89
PMD (dsPIC33EPXXXGP50X Devices)	95
PMD (dsPIC33EPXXXMC20X Devices).....	96
PMD (dsPIC33EPXXXMC50X Devices).....	95
PMD (PIC24EPXXXGP20X Devices)	94